4V Drive Nch MOS FET **RK7002A**

●Structure

Silicon N-channel MOS FET transistor

● Features

- 1) Low on-resistance.
- 2) High ESD
- 3) High-speed switching.
- 4) Low-voltage drive (4V).
- 5) Drive circuits can be simple.
- 6) Parallel use is easy.

Applications

Switching

Packaging specifications

	Package	Taping
	Code	T116
Туре	Basic ordering unit (pieces)	3000
RK7002A		0

●Absolute maximum ratings (Ta=25°C)

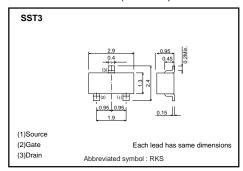
Parameter		Symbol	Limits	Unit
Drain-source voltage		VDSS	60	V
Gate-source voltage		Vgss	±20	V
Drain current	Continuous	ΙD	±300	mA
	Pulsed	IDP*1	±1.2	А
Source current (Body diode)	Continuous	Is	200	mA
	Pulsed	Isp*1	0.8	А
Total power dissipation		Po*2	200	mW
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Thermal resistance

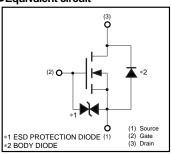
Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a)*	625	°C / W

^{*} With each pin mounted on the recommended land.

●External dimensions (Unit : mm)



●Equivalent circuit



* A protection diode has been built in between the gate and the source to protect against static electricity when the product is in use. Use the protection circuit when fixed voltages are exceeded.

^{*1} Pw≤10μs, Duty cycle≤1%
*2 With each pin mounted on the recommended land.

●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	
Gate leakage current	Igss	-	-	±10	μΑ	Vgs=±20V, Vps=0V	
Drain-source breakdown voltage	V (BR) DSS	60	-	-	V	In=1mA, Vgs=0V	
Drain cutoff current	IDSS	-	-	1	μΑ	VDS=60V, VGS=0V	
Gate threshold voltage	VGS (th)	1	-	2.5	V	VDS=10V, ID=1mA	
Drain-source on-state resistance	D *	-	0.7	1.0	Ω	In=300mA, Vgs=10V	
	RDS (on)*	-	1.1	1.5	1 22	In=300mA, Vgs=4V	
Forward transfer admittance	I Yfs I*	0.2	-	-	S	VDS=10V, ID=300mA	
Input capacitance	Ciss	-	33	-	pF	V _{DS} =10V	
Output capacitance	Coss	-	14	-	pF	Vgs=0V	
Reverse transfer capacitance	Crss	-	9	-	pF	f=1MHz	
Turn-on delay time	td (on)*	-	6	-	ns	ID=150mA, VDD≒30V	
Rise time	tr*	-	5	-	ns	V _G s=10V	
Turn-off delay time	td (off)*	-	13	-	ns	RL=200Ω	
Fall time	tr*	-	80	-	ns	R _G =10Ω	
Total gate charge	Q _g *	_	3	6	nC	V _{DD} ≒30V	
Gate-source charge	Q _{gs} *	_	0.6	-	nC	V _G s=10V	
Gate-drain charge	Q _{gd} *	_	0.5	-	nC	ID=200mA	

^{*} Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V _{SD} *	-	ı	1.2	V	I _S =300mA, V _{GS} =0V

^{*}Pulsed

Electrical characteristic curves

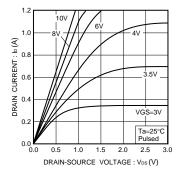


Fig.1 Typical output characteristics

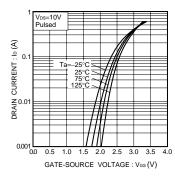


Fig.2 Typical transfer characteristics

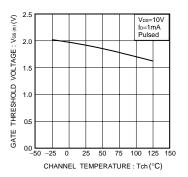


Fig.3 Gate threshold voltage vs. channel temperature

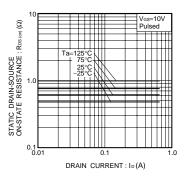


Fig.4 Static drain-source on-state resistance vs. drain current (I)

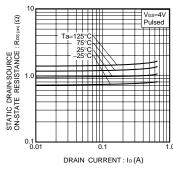


Fig.5 Static drain-source on-state resistance vs. drain current (II)

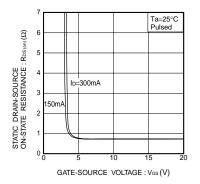


Fig.6 Static drain-source on-state resistance vs. gate-source voltage

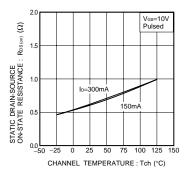


Fig.7 Static drain-source on-state resistance vs. channel temperature

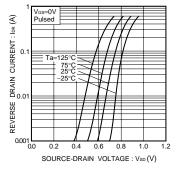


Fig.8 Reverse drain current vs. source-drain voltage (I)

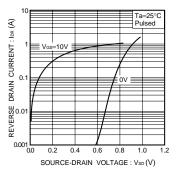


Fig.9 Reverse drain current vs. source-drain voltage (II)

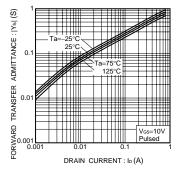


Fig.10 Forward transfer admittance vs. drain current

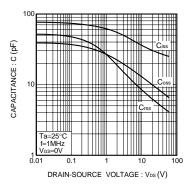


Fig.11 Typical capacitance vs. drain-source voltage

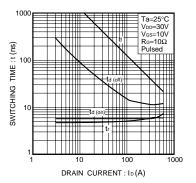


Fig.12 Switching characteristics (See Figures 13 and 14 for the measurement circuit and resultant waveforms)

•Switching characteristics measurement circuit

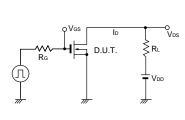


Fig.13 Switching time measurement circuit

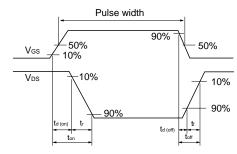


Fig.14 Switching time waveforms

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